Atmel SAM D21E / SAM D21G / SAM D21J

SMART ARM-Based Microcontroller

DATASHEET SUMMARY

Description

The Atmel® | SMART™ SAM D21 is a series of low-power microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, and ranging from 32- to 64-pins with up to 256KB Flash and 32KB of SRAM. The SAM D21 devices operate at a maximum frequency of 48MHz and reach 2.46 CoreMark/MHz. They are designed for simple and intuitive migration with identical peripheral modules, hex compatible code, identical linear address map and pin compatible migration paths between all devices in the product series. All devices include intelligent and flexible peripherals, Atmel Event System for inter-peripheral signaling, and support for capacitive touch button, slider and wheel user interfaces.

The Atmel SAM D21 devices provide the following features: In-system programmable Flash, twelve-channel direct memory access (DMA) controller, 12 channel Event System, programmable interrupt controller, up to 52 programmable I/O pins, 32-bit real-time clock and calendar, up to five 16-bit Timer/Counters (TC) and three 24-bit Timer/Counters for Control (TCC), where each TC can be configured to perform frequency and waveform generation, accurate program execution timing or input capture with time and frequency measurement of digital signals. The TCs can operate in 8- or 16-bit mode, selected TCs can be cascaded to form a 32-bit TC, and three timer/counters have extended functions optimized for motor, lighting and other control applications. The series provide one full-speed USB 2.0 embedded host and device interface; up to six Serial Communication Modules (SERCOM) that each can be configured to act as an USART, UART, SPI, I^2C up to 3.4MHz, SMBus, PMBus, and LIN slave; two-channel I^2S interface; up to twenty-channel 350ksps 12-bit ADC with programmable gain and optional oversampling and decimation supporting up to 16-bit resolution, one 10-bit 350ksps DAC, two analog comparators with window mode, Peripheral Touch Controller supporting up to 256 buttons, sliders, wheels and proximity sensing; programmable Watchdog Timer, brown-out detector and power-on reset and two-pin Serial Wire Debug (SWD) program and debug interface.

All devices have accurate and low-power external and internal oscillators. All oscillators can be used as a source for the system clock. Different clock domains can be independently configured to run at different frequencies, enabling power saving by running each peripheral at its optimal clock frequency, and thus maintaining a high CPU frequency while reducing power consumption.

The SAM D21 devices have two software-selectable sleep modes, idle and standby. In idle mode the CPU is stopped while all other functions can be kept running. In standby all clocks and functions are stopped expect those selected to continue running. The device supports SleepWalking. This feature allows the peripheral to wake up from sleep based on predefined conditions, and thus allows the CPU to wake up only when needed, e.g. when a threshold is crossed or a result is ready. The Event System supports synchronous and asynchronous events, allowing peripherals to receive, react to and send events even in standby mode.

The Flash program memory can be reprogrammed in-system through the SWD interface. The same interface can be used for non-intrusive on-chip debug of application code. A boot loader running in the device can use any communication interface to download and upgrade the application program in the Flash memory.

The Atmel SAM D21 devices are supported with a full suite of program and system development tools, including C compilers, macro assemblers, program debugger/simulators, programmers and evaluation kits.

Features

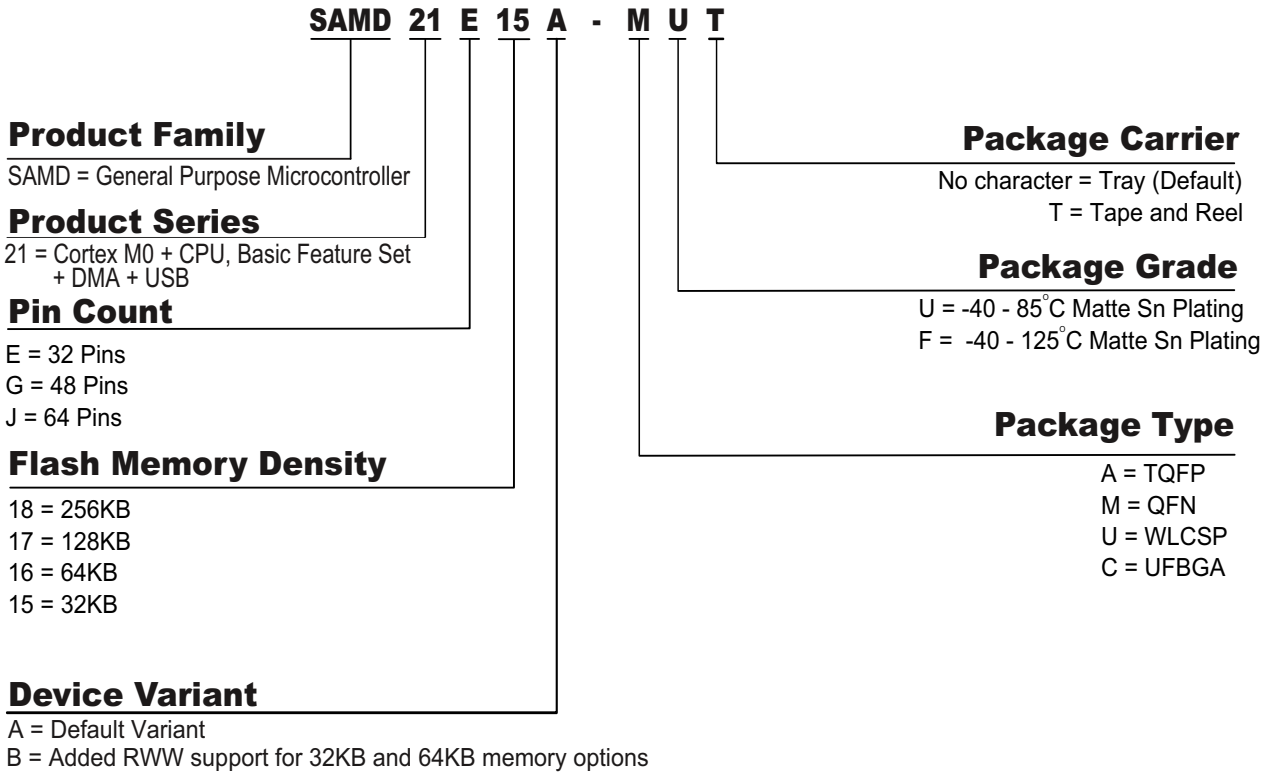
- Processor
  - ARM Cortex-M0+ CPU running at up to 48MHz
    - Single-cycle hardware multiplier
    - Micro Trace Buffer (MTB)
- Memories
  - 32/64/128/256KB in-system self-programmable Flash
  - 4/8/16/32KB SRAM Memory
- System
  - Power-on reset (POR) and brown-out detection (BOD)
  - Internal and external clock options with 48MHz Digital Frequency Locked Loop (DFLL48M) and 48MHz to 96MHz Fractional Digital Phase Locked Loop (FDPLL96M)
  - External Interrupt Controller (EIC)
  - 16 external interrupts
  - One non-maskable interrupt
  - Two-pin Serial Wire Debug (SWD) programming, test and debugging interface
- Low Power
  - Idle and standby sleep modes
  - SleepWalking peripherals
- Peripherals
  - 12-channel Direct Memory Access Controller (DMAC)
  - 12-channel Event System
  - Up to five 16-bit Timer/Counters (TC), configurable as either:
    - One 16-bit TC with compare/capture channels
    - One 8-bit TC with compare/capture channels
    - One 32-bit TC with compare/capture channels, by using two TCs
  - Three 24-bit Timer/Counters for Control (TCC), with extended functions:
    - Up to four compare channels with optional complementary output
    - Generation of synchronized pulse width modulation (PWM) pattern across port pins
    - Deterministic fault protection, fast decay and configurable dead-time between complementary output
    - Dithering that increase resolution with up to 5 bit and reduce quantization error
  - 32-bit Real Time Counter (RTC) with clock/calendar function
  - Watchdog Timer (WDT)
  - CRC-32 generator
  - One full-speed (12Mbps) Universal Serial Bus (USB) 2.0 interface
    - Embedded host and device function
    - Eight endpoints
  - Up to six Serial Communication Interfaces (SERCOM), each configurable to operate as either:
    - USART with full-duplex and single-wire half-duplex configuration
    - I^2C up to 3.4MHz
    - SPI
    - LIN slave
  - One two-channel Inter-IC Sound (I^2S) interface
  - One 12-bit, 350ksps Analog-to-Digital Converter (ADC) with up to 20 channels
    - Differential and single-ended input
    - 1/2x to 16x programmable gain stage
    - Automatic offset and gain error compensation
    - Oversampling and decimation in hardware to support 13-, 14-, 15- or 16-bit resolution
  - 10-bit, 350ksps Digital-to-Analog Converter (DAC)
  - Two Analog Comparators (AC) with window compare function
  - Peripheral Touch Controller (PTC)
    - 256-Channel capacitive touch and proximity sensing
- I/O
  - Up to 52 programmable I/O pins
- Drop in compatible with SAM D20
- Packages
  - 64-pin TQFP, QFN, UFBGA
  - 48-pin TQFP, QFN, WLCSP
  - 32-pin TQFP, QFN, WLCSP
- Operating Voltage
  - 1.62V – 3.63V

1. Configuration Summary

	SAM D21J	SAM D21G	SAM D21E
Pins	64	48	32
General Purpose I/O-pins (GPIOs)	52	38	26
Flash	256/128/64/32KB	256/128/64/32KB	256/128/64/32KB
SRAM	32/16/8/4KB	32/16/8/4KB	32/16/8/4KB
Timer Counter (TC) instances	5	3	3
Waveform output channels per TC instance	2	2	2
Timer Counter for Control (TCC) instances	3	3	3
Waveform output channels per TCC	8/4/2	8/4/2	6/4/2
DMA channels	12	12	12
USB interface	1	1	1
Serial Communication Interface (SERCOM) instances	6	6	4
Inter-IC Sound (I^2S) interface	1	1	1
Analog-to-Digital Converter (ADC) channels	20	14	10
Analog Comparators (AC)	2	2	2
Digital-to-Analog Converter (DAC) channels	1	1	1
Real-Time Counter (RTC)	Yes	Yes	Yes
RTC alarms	1	1	1
RTC compare values	1 32-bit value or 2 16-bit values	1 32-bit value or 2 16-bit values	1 32-bit value or 2 16-bit values
External Interrupt lines	16	16	16
Peripheral Touch Controller (PTC) X and Y lines	16x16	12x10	10x6
Maximum CPU frequency	48MHz		
Packages	QFN TQFP UFBGA	QFN TQFP WLCSP	QFN TQFP WLCSP
Oscillators	32.768kHz crystal oscillator (XOSC32K) 0.4-32MHz crystal oscillator (XOSC) 32.768kHz internal oscillator (OSC32K) 32kHz ultra-low-power internal oscillator (OSCULP32K) 8MHz high-accuracy internal oscillator (OSC8M) 48MHz Digital Frequency Locked Loop (DFLL48M) 96MHz Fractional Digital Phased Locked Loop (FDPLL96M)		

	SAM D21J	SAM D21G	SAM D21E
Event System channels	12	12	12
SW Debug Interface	Yes	Yes	Yes
Watchdog Timer (WDT)	Yes	Yes	Yes

2. Ordering Information



2.1 SAM D21E

2.1.1 Device Variant A

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E15A-AU	32K	4K	TQFP32	Tray
ATSAMD21E15A-AUT				Tape & Reel
ATSAMD21E15A-AF				Tray
ATSAMD21E15A-AFT				Tape & Reel
ATSAMD21E15A-MU			QFN32	Tray
ATSAMD21E15A-MUT				Tape & Reel
ATSAMD21E15A-MF				Tray
ATSAMD21E15A-MFT				Tape & Reel

2.1.1 Device Variant A (Continued)

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E16A-AU	64K	8K	TQFP32	Tray
ATSAMD21E16A-AUT				Tape & Reel
ATSAMD21E16A-AF				Tray
ATSAMD21E16A-AFT				Tape & Reel
ATSAMD21E16A-MU			QFN32	Tray
ATSAMD21E16A-MUT				Tape & Reel
ATSAMD21E16A-MF				Tray
ATSAMD21E16A-MFT				Tape & Reel
ATSAMD21E17A-AU	128K	16K	TQFP32	Tray
ATSAMD21E17A-AUT				Tape & Reel
ATSAMD21E17A-AF				Tray
ATSAMD21E17A-AFT				Tape & Reel
ATSAMD21E17A-MU			QFN32	Tray
ATSAMD21E17A-MUT				Tape & Reel
ATSAMD21E17A-MF				Tray
ATSAMD21E17A-MFT				Tape & Reel
ATSAMD21E18A-AU	256K	32K	TQFP32	Tray
ATSAMD21E18A-AUT				Tape & Reel
ATSAMD21E18A-AF				Tray
ATSAMD21E18A-AFT				Tape & Reel
ATSAMD21E18A-MU			QFN32	Tray
ATSAMD21E18A-MUT				Tape & Reel
ATSAMD21E18A-MF				Tray
ATSAMD21E18A-MFT				Tape & Reel

2.1.2 Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E15B-AU	32K	4K	TQFP32	Tray
ATSAMD21E15B-AUT				Tape & Reel
ATSAMD21E15B-AF				Tray
ATSAMD21E15B-AFT				Tape & Reel
ATSAMD21E15B-MU			QFN32	Tray
ATSAMD21E15B-MUT				Tape & Reel
ATSAMD21E15B-MF				Tray
ATSAMD21E15B-MFT				Tape & Reel
ATSAMD21E15B-UUT	32K	4K	WLCSP35	Tape & Reel
ATSAMD21E16B-AU	64K	8K	TQFP32	Tray
ATSAMD21E16B-AUT				Tape & Reel
ATSAMD21E16B-AF				Tray
ATSAMD21E16B-AFT				Tape & Reel
ATSAMD21E16B-MU			QFN32	Tray
ATSAMD21E16B-MUT				Tape & Reel
ATSAMD21E16B-MF				Tray
ATSAMD21E16B-MFT				Tape & Reel
ATSAMD21E16B-UUT	64K	8K	WLCSP35	Tape & Reel

2.2 SAM D21G

2.2.1 Device Variant A

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G15A-AU	32K	4K	TQFP48	Tray
ATSAMD21G15A-AUT				Tape & Reel
ATSAMD21G15A-AF				Tray
ATSAMD21G15A-AFT				Tape & Reel
ATSAMD21G15A-MU			QFN48	Tray
ATSAMD21G15A-MUT				Tape & Reel
ATSAMD21G15A-MF				Tray
ATSAMD21G15A-MFT				Tape & Reel

2.2.1 Device Variant A (Continued)

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G16A-AU	64K	8K	TQFP48	Tray
ATSAMD21G16A-AUT				Tape & Reel
ATSAMD21G16A-AF				Tray
ATSAMD21G16A-AFT				Tape & Reel
ATSAMD21G16A-MU			QFN48	Tray
ATSAMD21G16A-MUT				Tape & Reel
ATSAMD21G16A-MF				Tray
ATSAMD21G16A-MFT				Tape & Reel
ATSAMD21G17A-AU	128K	16K	TQFP48	Tray
ATSAMD21G17A-AUT				Tape & Reel
ATSAMD21G17A-AF				Tray
ATSAMD21G17A-AFT				Tape & Reel
ATSAMD21G17A-MU			QFN48	Tray
ATSAMD21G17A-MUT				Tape & Reel
ATSAMD21G17A-MF				Tray
ATSAMD21G17A-MFT				Tape & Reel
ATSAMD21G17A-UUT			WLCSP45	Tape & Reel
ATSAMD21G18A-AU	256K	32K	TQFP48	Tray
ATSAMD21G18A-AUT				Tape & Reel
ATSAMD21G18A-AF				Tray
ATSAMD21G18A-AFT				Tape & Reel
ATSAMD21G18A-MU			QFN48	Tray
ATSAMD21G18A-MUT				Tape & Reel
ATSAMD21G18A-MF				Tray
ATSAMD21G18A-MFT				Tape & Reel
ATSAMD21G18A-UUT			WLCSP45	Tape & Reel

2.2.2 Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G15B-AU	32K	4K	TQFP48	Tray
ATSAMD21G15B-AUT				Tape & Reel
ATSAMD21G15B-AF				Tray
ATSAMD21G15B-AFT				Tape & Reel
ATSAMD21G15B-MU			QFN48	Tray
ATSAMD21G15B-MUT				Tape & Reel
ATSAMD21G15B-MF				Tray
ATSAMD21G15B-MFT				Tape & Reel
ATSAMD21G16B-AU	64K	8K	TQFP48	Tray
ATSAMD21G16B-AUT				Tape & Reel
ATSAMD21G16B-AF				Tray
ATSAMD21G16B-AFT				Tape & Reel
ATSAMD21G16B-MU			QFN48	Tray
ATSAMD21G16B-MUT				Tape & Reel
ATSAMD21G16B-MF				Tray
ATSAMD21G16B-MFT				Tape & Reel

2.3 SAM D21J

2.3.1 Device Variant A

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J15A-AU	32K	4K	TQFP64	Tray
ATSAMD21J15A-AUT				Tape & Reel
ATSAMD21J15A-AF				Tray
ATSAMD21J15A-AFT				Tape & Reel
ATSAMD21J15A-MU			QFN64	Tray
ATSAMD21J15A-MUT				Tape & Reel
ATSAMD21J15A-MF				Tray
ATSAMD21J15A-MFT				Tape & Reel

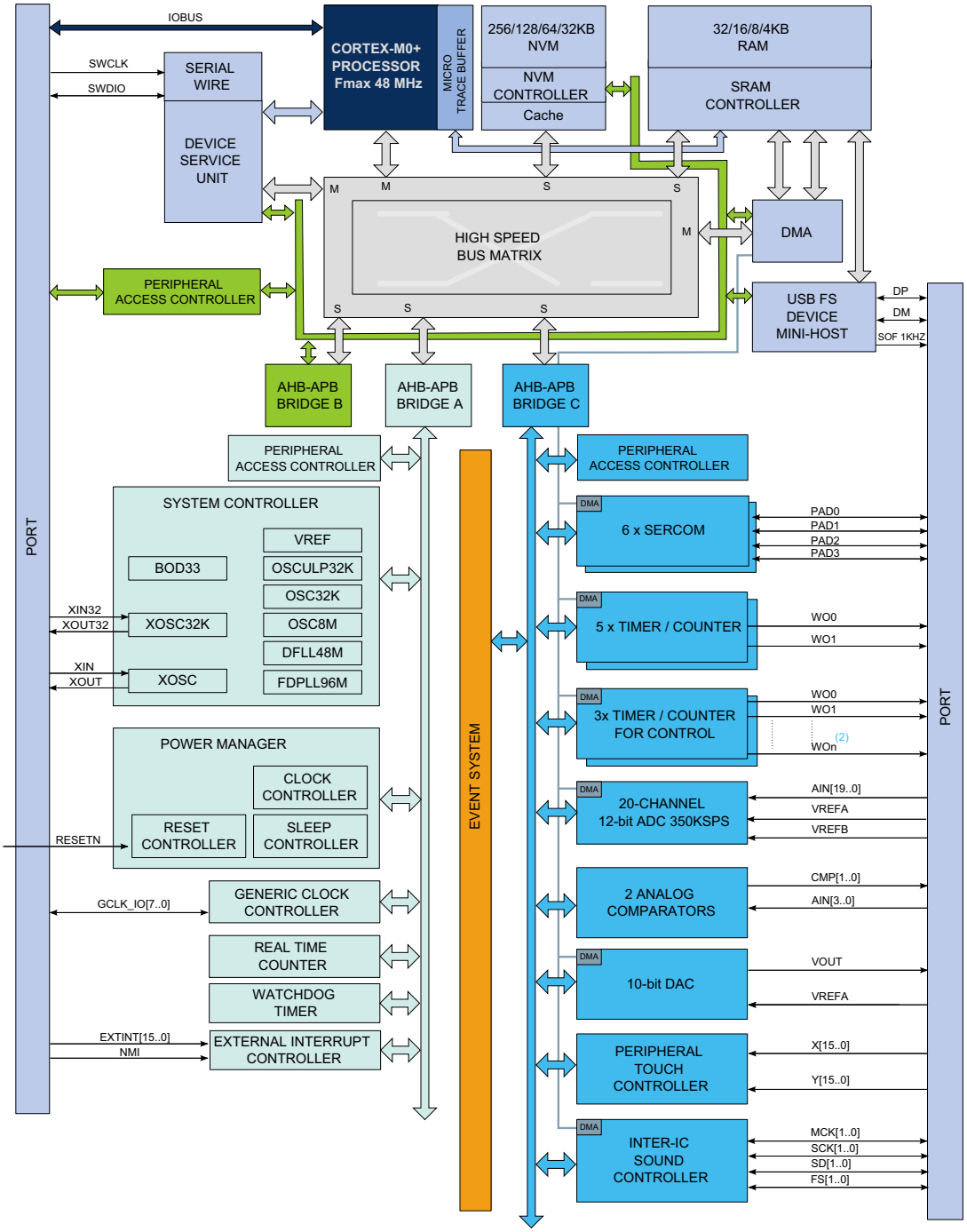
2.3.1 Device Variant A (Continued)

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J16A-AU	64K	8K	TQFP64	Tray
ATSAMD21J16A-AUT				Tape & Reel
ATSAMD21J16A-AF				Tray
ATSAMD21J16A-AFT				Tape & Reel
ATSAMD21J16A-MU			QFN64	Tray
ATSAMD21J16A-MUT				Tape & Reel
ATSAMD21J16A-MF				Tray
ATSAMD21J16A-MFT				Tape & Reel
ATSAMD21J16A-CU			UFBGA64	Tray
ATSAMD21J16A-CUT				Tape & Reel
ATSAMD21J17A-AU	128K	16K	TQFP64	Tray
ATSAMD21J17A-AUT				Tape & Reel
ATSAMD21J17A-AF				Tray
ATSAMD21J17A-AFT				Tape & Reel
ATSAMD21J17A-MU			QFN64	Tray
ATSAMD21J17A-MUT				Tape & Reel
ATSAMD21J17A-MF				Tray
ATSAMD21J17A-MFT				Tape & Reel
ATSAMD21J17A-CU			UFBGA64	Tray
ATSAMD21J17A-CUT				Tape & Reel
ATSAMD21J18A-AU	256K	32K	TQFP64	Tray
ATSAMD21J18A-AUT				Tape & Reel
ATSAMD21J18A-AF				Tray
ATSAMD21J18A-AFT				Tape & Reel
ATSAMD21J18A-MU			QFN64	Tray
ATSAMD21J18A-MUT				Tape & Reel
ATSAMD21J18A-MF				Tray
ATSAMD21J18A-MFT				Tape & Reel
ATSAMD21J18A-CU			UFBGA64	Tray
ATSAMD21J18A-CUT				Tape & Reel

2.3.2 Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J15B-AU	32K	4K	TQFP64	Tray
ATSAMD21J15B-AUT				Tape & Reel
ATSAMD21J15B-AF				Tray
ATSAMD21J15B-AFT				Tape & Reel
ATSAMD21J15B-MU			QFN64	Tray
ATSAMD21J15B-MUT				Tape & Reel
ATSAMD21J15B-MF				Tray
ATSAMD21J15B-MFT				Tape & Reel
ATSAMD21J16B-AU	64K	8K	TQFP64	Tray
ATSAMD21J16B-AUT				Tape & Reel
ATSAMD21J16B-AF				Tray
ATSAMD21J16B-AFT				Tape & Reel
ATSAMD21J16B-MU			QFN64	Tray
ATSAMD21J16B-MUT				Tape & Reel
ATSAMD21J16B-MF				Tray
ATSAMD21J16B-MFT				Tape & Reel
ATSAMD21J16B-CU			UFBGA64	Tray
ATSAMD21J16B-CUT				Tape & Reel

3. Block Diagram

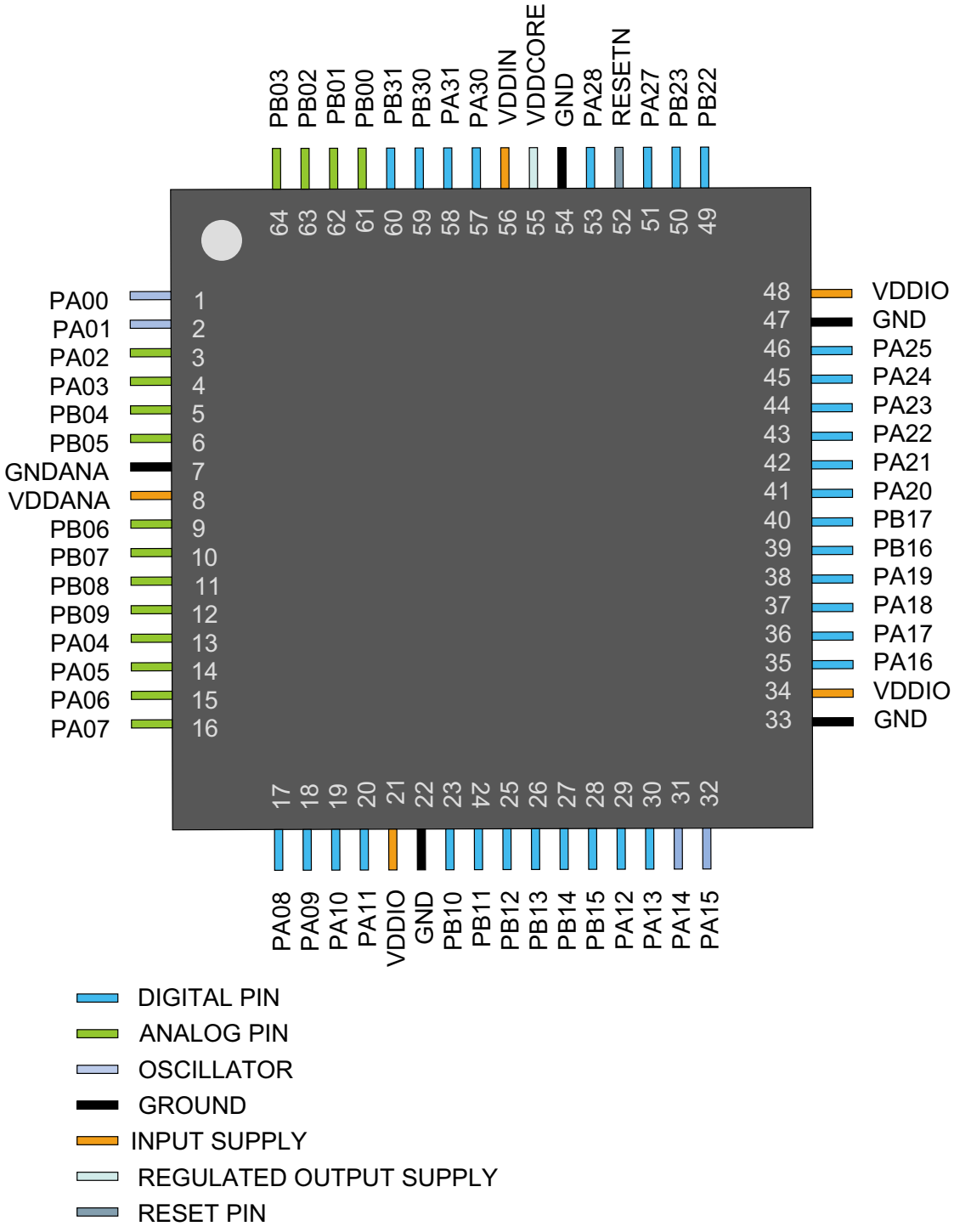


1. Some products have different number of SERCOM instances, Timer/Counter instances, PTC signals and ADC signals.
2. The three TCC instances have different configurations, including the number of Waveform Output (WO) lines.

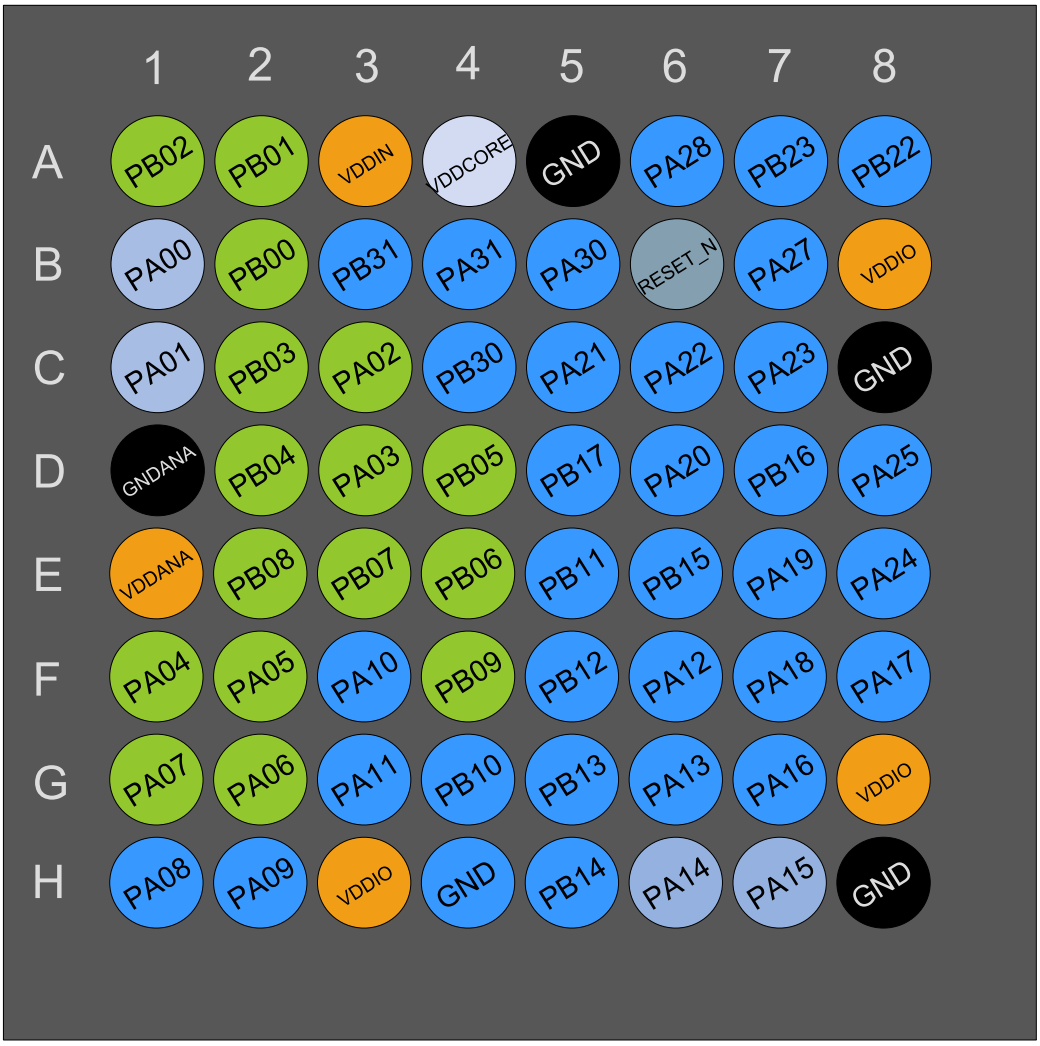
4. Pinout

4.1 SAM D21J

4.1.1 QFN64 / TQFP64



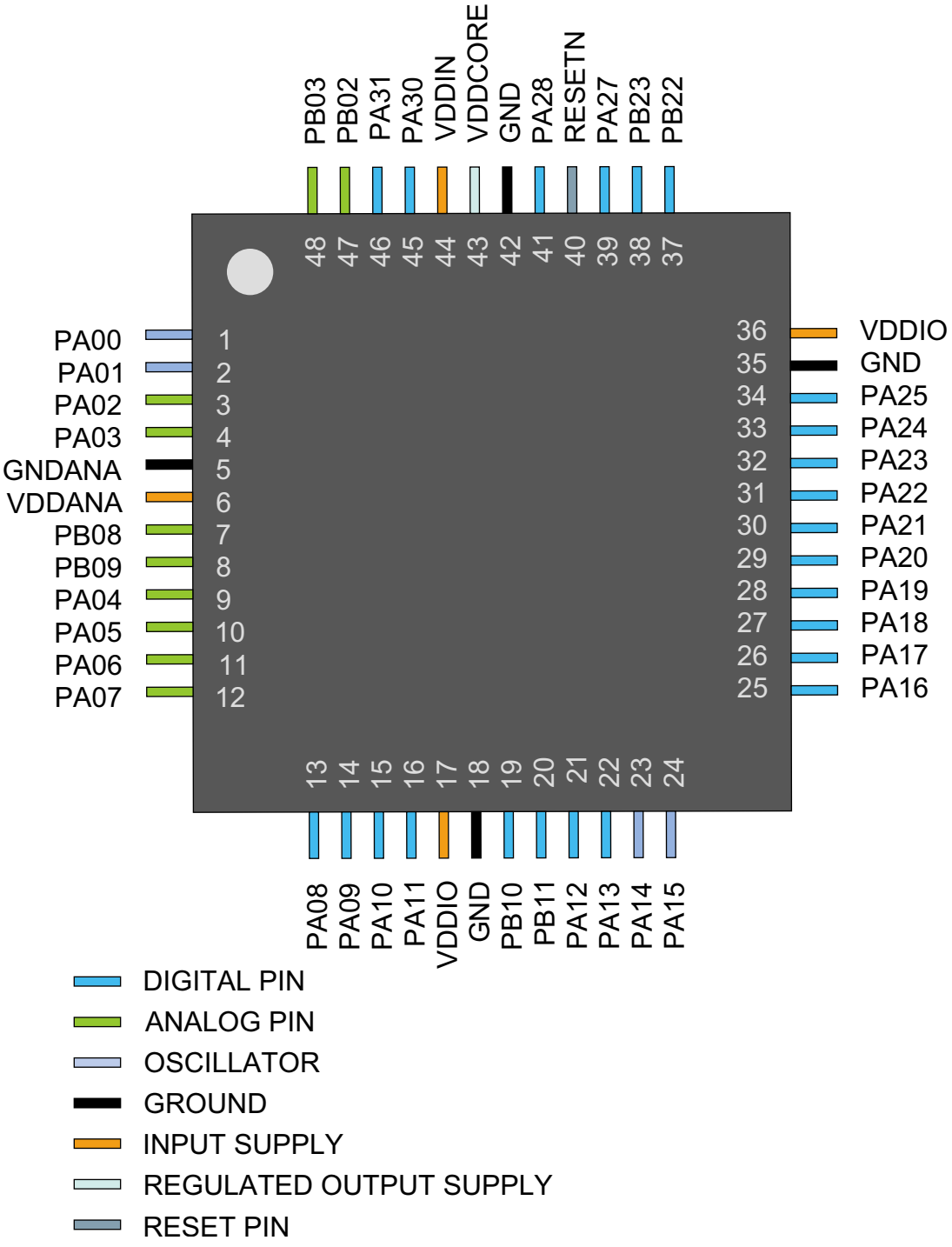
4.1.2 UFBGA64



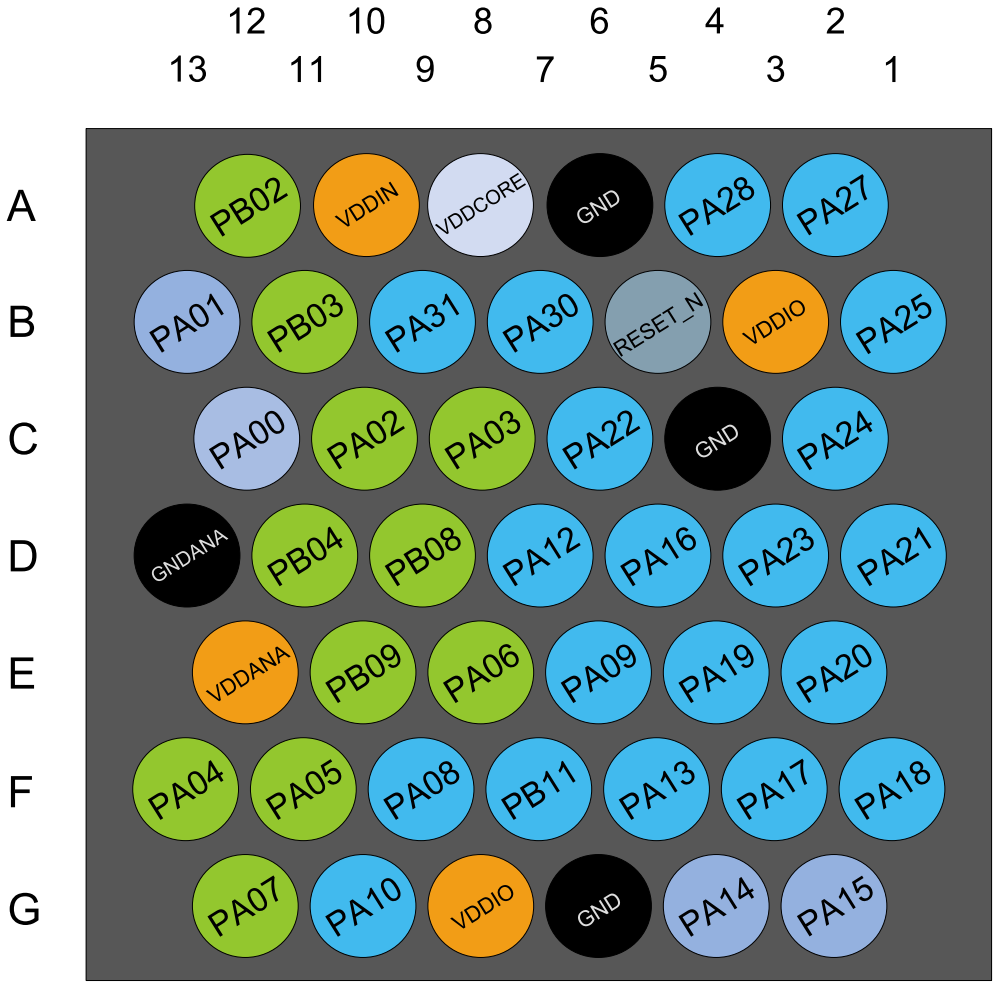
- DIGITAL PIN
- ANALOG PIN
- OSCILLATOR
- GROUND
- INPUT SUPPLY
- REGULATED OUTPUT SUPPLY
- RESET PIN

4.2 SAM D21G

4.2.1 QFN48 / TQFP48

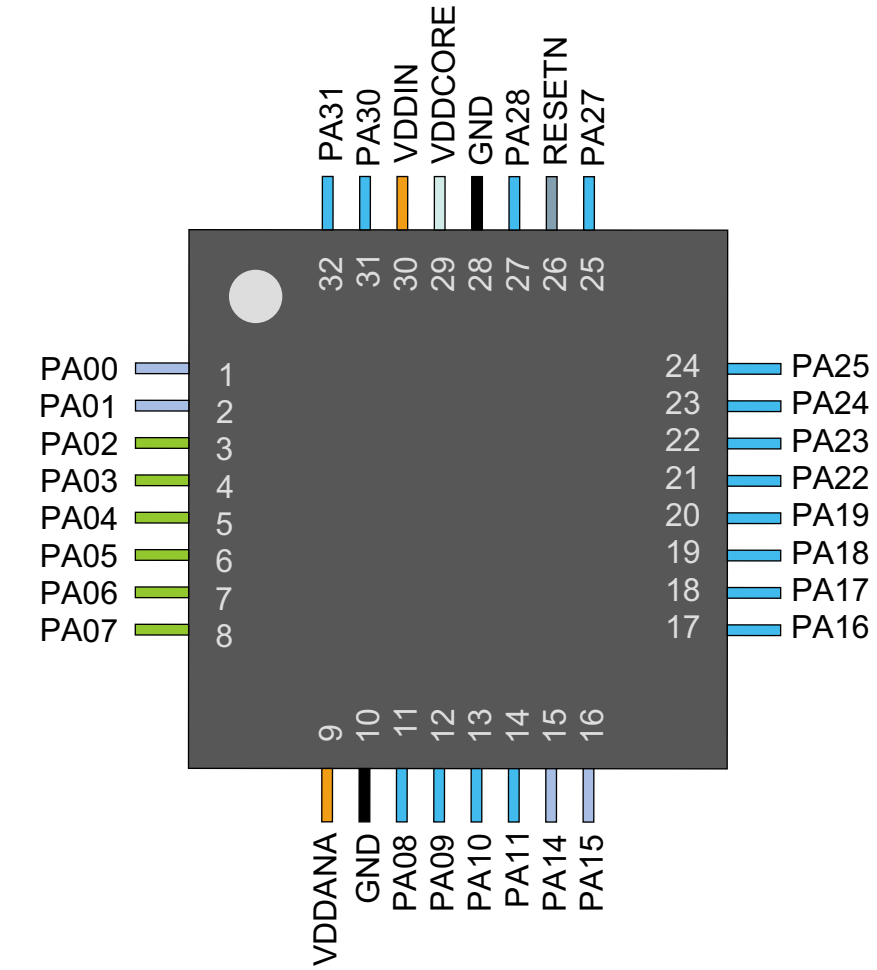


4.2.2 WLCSP45

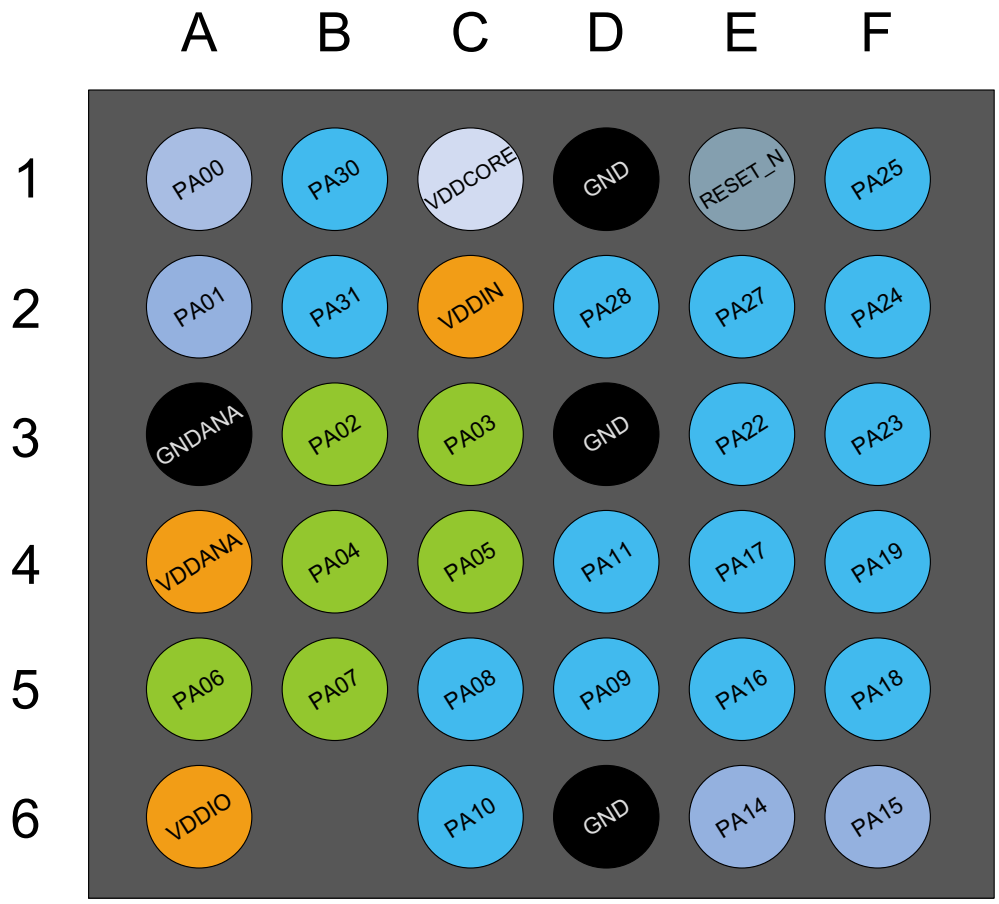

12 10 8 6 4 2
13 11 9 7 5 3 1
A
B
C
D
E
F
G
PB02
VDDIN
VDDCORE
GND
PA28
PA27
PA01
PB03
PA31
PA30
RESET_N
VDDIO
PA25
PA00
PA02
PA03
PA22
GND
PA24
GNDANA
PB04
PB08
PA12
PA16
PA23
PA21
VDDANA
PB09
PA06
PA09
PA19
PA20
PA04
PA05
PA08
PB11
PA13
PA17
PA18
PA07
PA10
VDDIO
GND
PA14
PA15
DIGITAL PIN
ANALOG PIN
OSCILLATOR
GROUND
INPUT SUPPLY
REGULATED OUTPUT SUPPLY
RESET PIN

4.3 SAM D21E

4.3.1 QFN32 / TQFP32

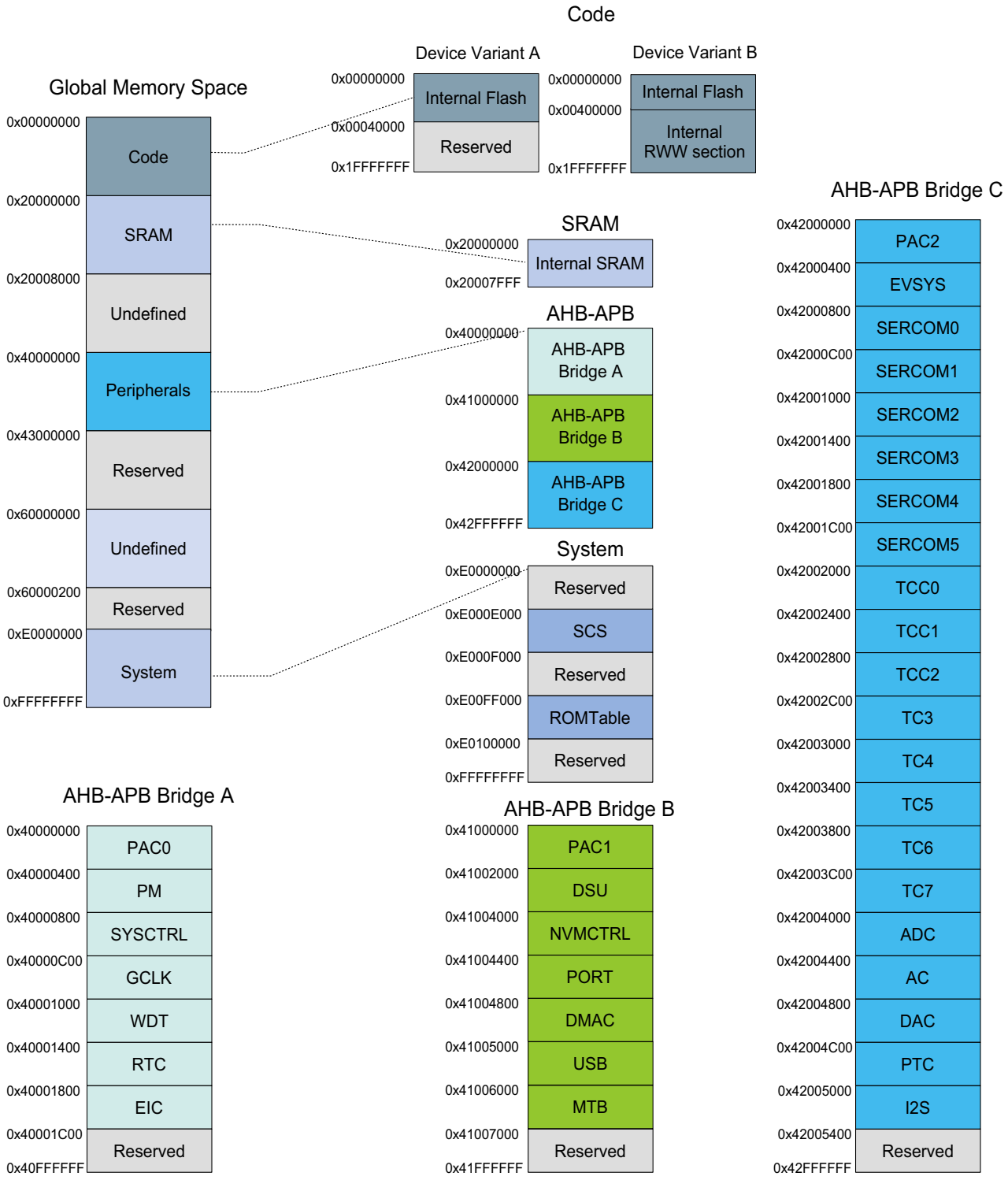


4.3.2 WLCSP35


A B C D E F
1 2 3 4 5 6
PA00 PA30 VDDCORE GND RESET_N PA25
PA01 PA31 VDDIN PA28 PA27 PA24
GNDANA PA02 PA03 GND PA22 PA23
VDDANA PA04 PA05 PA11 PA17 PA19
PA06 PA07 PA08 PA09 PA16 PA18
VDDIO PA10 GND PA14 PA15
DIGITAL PIN
ANALOG PIN
OSCILLATOR
GROUND
INPUT SUPPLY
REGULATED OUTPUT SUPPLY
RESET PIN

5. Product Mapping

Figure 5-1. Atmel | SMART SAM D21 Product Mapping



This figure represents the full configuration of the Atmel® SAM D21 with maximum flash and SRAM capabilities and a full set of peripherals. Refer to the "Configuration Summary" on page 3 for details.

6. Processor And Architecture

6.1 Cortex M0+ Processor

The Atmel | SMART SAM D21 implements the ARM® Cortex™-M0+ processor, which is based on the ARMv6 Architecture and Thumb®-2 ISA. The Cortex M0+ is 100% instruction set compatible with its predecessor, the Cortex-M0 processor, and upward compatible to Cortex-M3 and M4 processors.

For more information refer to www.arm.com.

6.1.1 Cortex M0+ Configuration

Features	Configuration option	Atmel | SMART SAM D21 configuration
Interrupts	External interrupts 0-32	32
Data endianness	Little-endian or big-endian	Little-endian
SysTick timer	Present or absent	Present
Number of watchpoint comparators	0, 1, 2	2
Number of breakpoint comparators	0, 1, 2, 3, 4	4
Halting debug support	Present or absent	Present
Multiplier	Fast or small	Fast (single cycle)
Single-cycle I/O port	Present or absent	Present
Wake-up interrupt controller	Supported or not supported	Not supported
Vector Table Offset Register	Present or absent	Present
Unprivileged/Privileged support	Present or absent	Absent(1)
Memory Protection Unit	Not present or 8-region	Not present
Reset all registers	Present or absent	Absent
Instruction fetch width	16-bit only or mostly 32-bit	32-bit

Note: 1. All software run in privileged mode only

The ARM Cortex-M0+ core has two bus interfaces:

- Single 32-bit AMBA®-3 AHB-Lite™ system interface that provides connections to peripherals and all system memory, including flash and RAM
- Single 32-bit I/O port bus interfacing to the PORT with one-cycle loads and stores

7. Packaging Information

7.1 Thermal Considerations

7.1.1 Thermal Resistance Data

Table 7-1 summarizes the thermal resistance data depending on the package.

Table 7-1. Thermal Resistance Data

Package Type	θ_{JA}	θ_{JC}
32-pin TQFP	64.7 °C/W	23.1 °C/W
48-pin TQFP	63.6 °C/W	12.2 °C/W
64-pin TQFP	60.9 °C/W	12.2 °C/W
32-pin QFN	40.9 °C/W	15.2 °C/W
48-pin QFN	32.0 °C/W	10.9 °C/W
64-pin QFN	32.5 °C/W	10.7 °C/W

7.1.2 Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

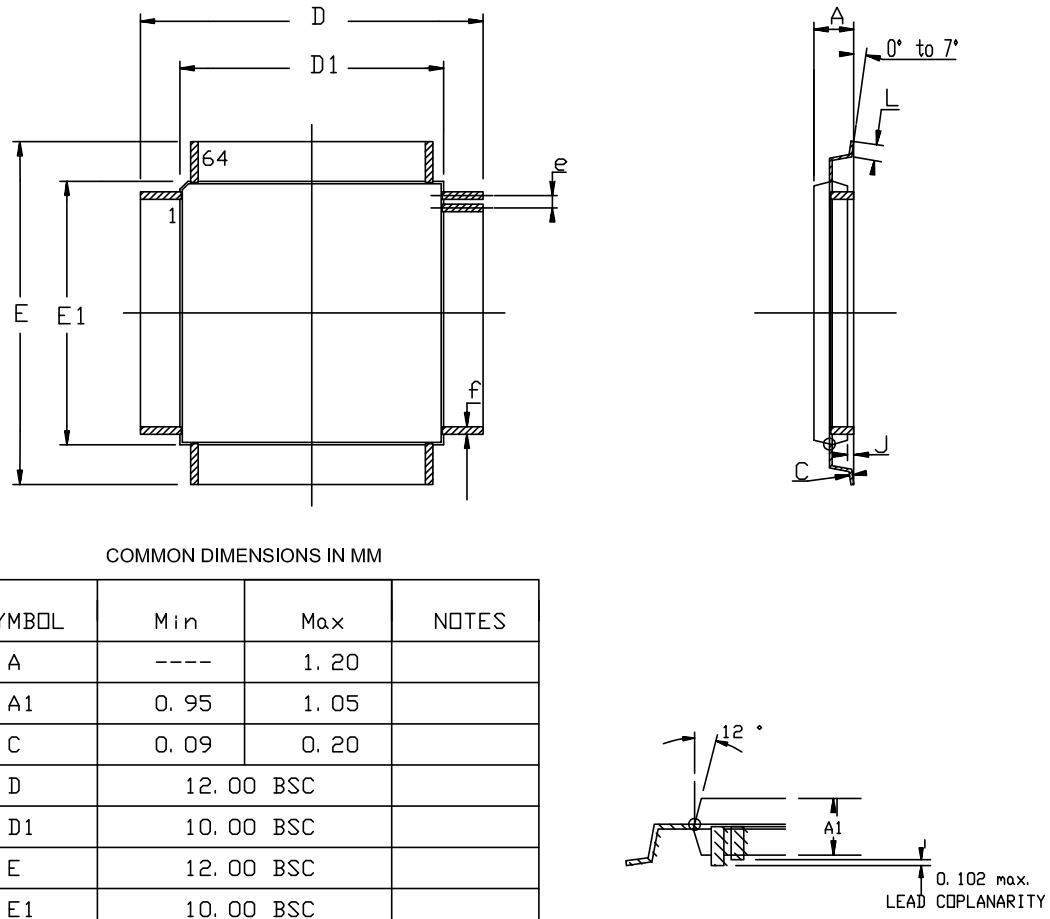
where:

- θ_{JA} = package thermal resistance, Junction-to-ambient (°C/W), provided in Table 7-1.
- θ_{JC} = package thermal resistance, Junction-to-case thermal resistance (°C/W), provided in Table 7-1.
- $\theta_{HEATSINK}$ = cooling device thermal resistance (°C/W), provided in the device datasheet.
- P_D = device power consumption (W).
- T_A = ambient temperature (°C).

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

7.2 Package Drawings

7.2.1 64-pin TQFP



COMMON DIMENSIONS IN MM

SYMBOL	Min	Max	NOTES
A	----	1.20	
A1	0.95	1.05	
C	0.09	0.20	
D	12.00 BSC		
D1	10.00 BSC		
E	12.00 BSC		
E1	10.00 BSC		
J	0.05	0.15	
L	0.45	0.75	
e	0.50 BSC		
f	0.17	0.27	

Table 7-2. Device and Package Maximum Weight

300	mg

Table 7-3. Package Characteristics

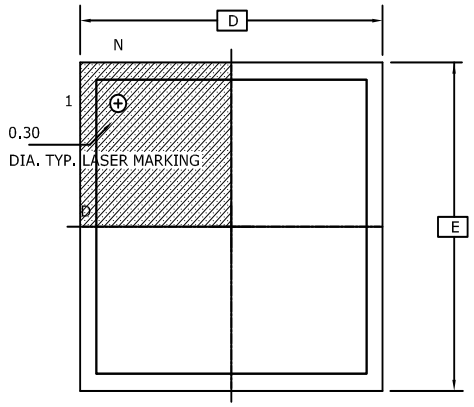
Moisture Sensitivity Level	MSL3

Table 7-4. Package Reference

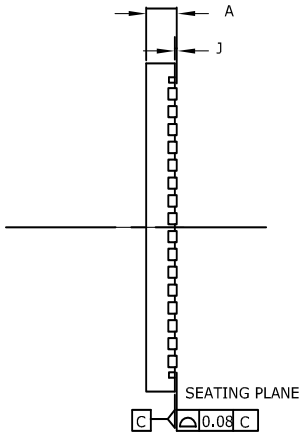
JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

7.2.2 64-pin QFN

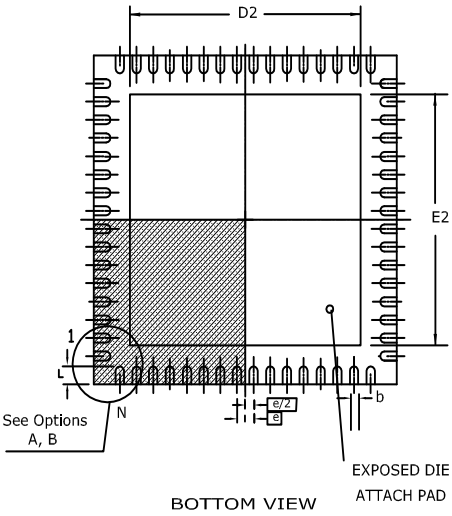
DRAWINGS NOT SCALED



TOP VIEW



SIDE VIEW



BOTTOM VIEW

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	-----	1.00	
D/E		9.00 BSC		
D2/E2	4.60	4.70	4.80	
J	0.00	-----	0.05	
b	0.15	0.20	0.25	
e		0.50 BSC		
L	0.30	0.40	0.55	
N		64		

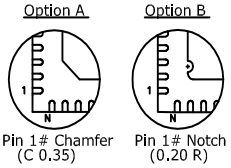


Table 7-5. Device and Package Maximum Weight

200	mg

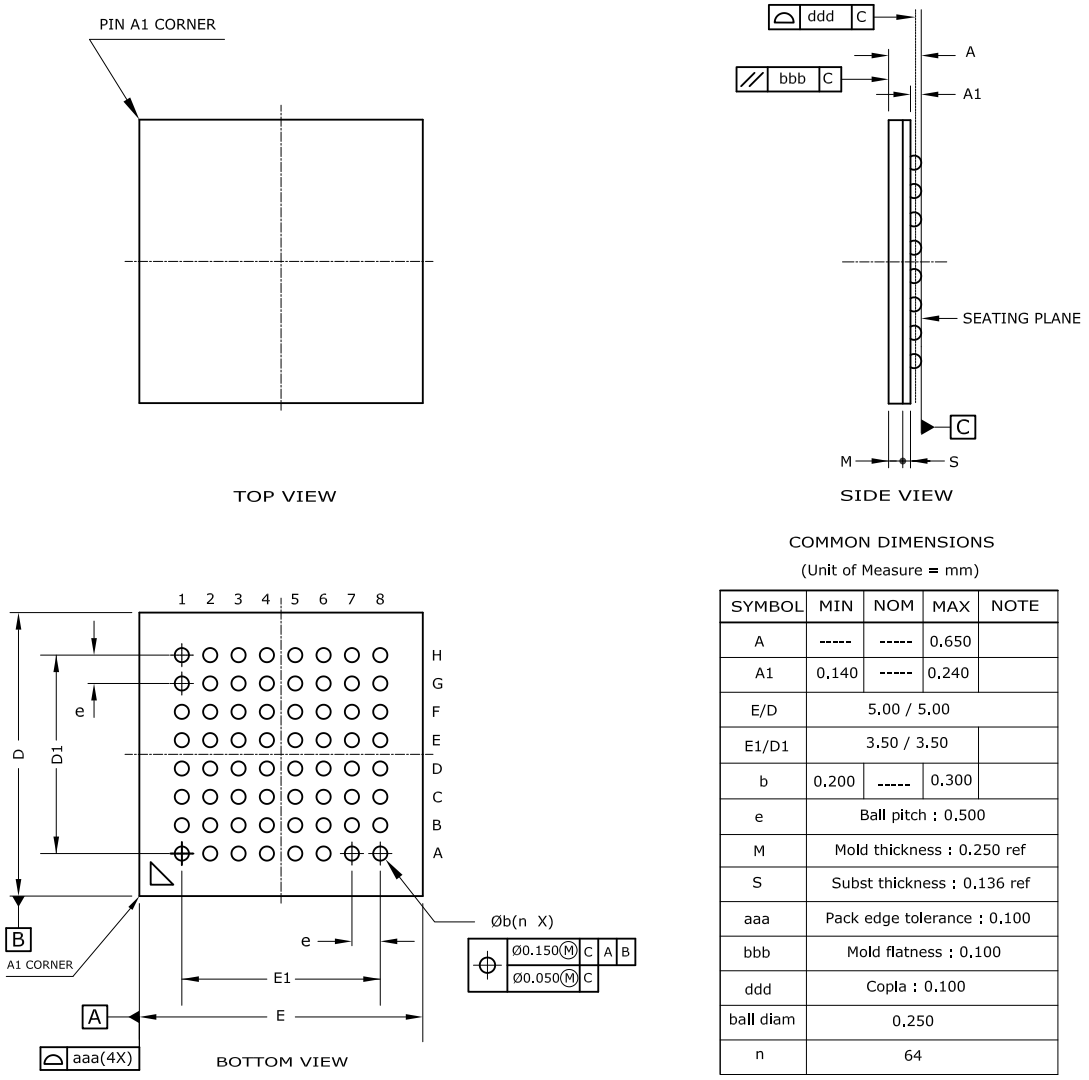
Table 7-6. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 7-7. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

7.2.3 64-ball UFBGA



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	0.650	
A1	0.140	-----	0.240	
E/D	5.00 / 5.00			
E1/D1	3.50 / 3.50			
b	0.200	-----	0.300	
e	Ball pitch : 0.500			
M	Mold thickness : 0.250 ref			
S	Subst thickness : 0.136 ref			
aaa	Pack edge tolerance : 0.100			
bbb	Mold flatness : 0.100			
ddd	Copla : 0.100			
ball diam	0.250			
n	64			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-280, Variation UCCBB for proper dimensions, tolerances, datums, etc.
2. Array as seen from the bottom of the package.
3. Dimension A includes stand-off height A1, package body thickness, and lid height, but does not include attached features.
4. Dimension b is measured at the maximum ball diameter, parallel to primary datum C.

Table 7-8. Device and Package Maximum Weight

27.4	mg

Table 7-9. Package Characteristics

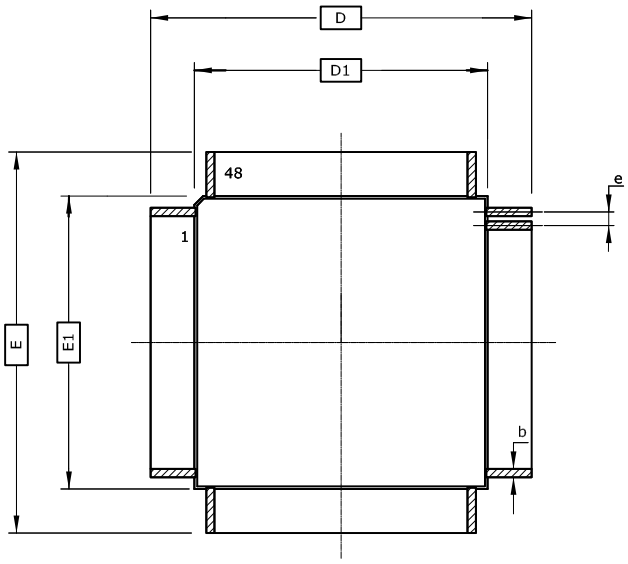
Moisture Sensitivity Level	MSL3

Table 7-10. Package Reference

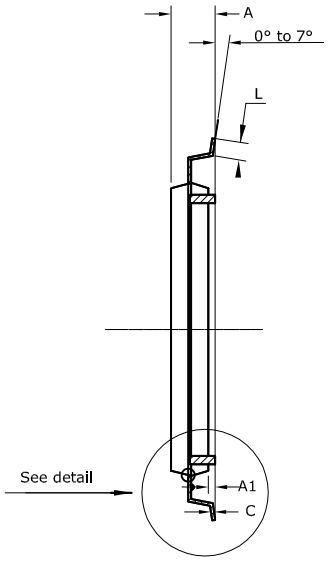
JEDEC Drawing Reference	MO-220
JESD97 Classification	E8

7.2.4 48-pin TQFP

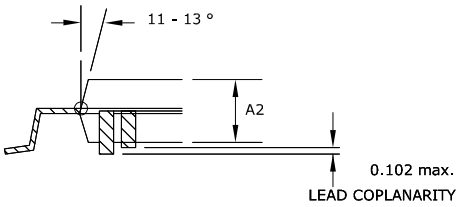
DRAWINGS NOT SCALED



TOP VIEW



SIDE VIEW



DETAIL VIEW

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.05	-----	0.15	
A2	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E	9.00 BSC			
D1/E1	7.00 BSC			
L	0.45	-----	0.75	
b	0.17	-----	0.27	
e	0.50 BSC			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ABC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

Table 7-11. Device and Package Maximum Weight

140	mg

Table 7-12. Package Characteristics

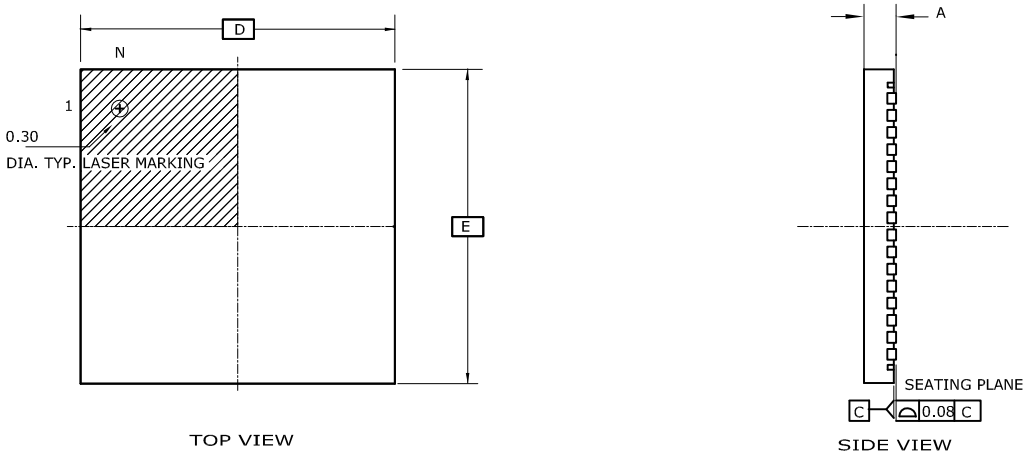
Moisture Sensitivity Level	MSL3

Table 7-13. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

7.2.5 48-pin QFN

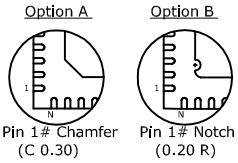
DRAWINGS NOT SCALED



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.85	0.90	
D/E		7.00 BSC		
D2/E2	5.05	5.15	5.25	
b	0.18	0.25	0.30	
e		0.50 BSC		
L	0.30	0.40	0.50	
N		48		



Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-220, Variation VKKD-4, for proper dimensions, tolerances, datums, etc.
2. Dimension b applies to metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
If the terminal has the optical radius on the other end of the terminal, the dimension should not be measured in that radius area.

Table 7-14. Device and Package Maximum Weight

140	mg

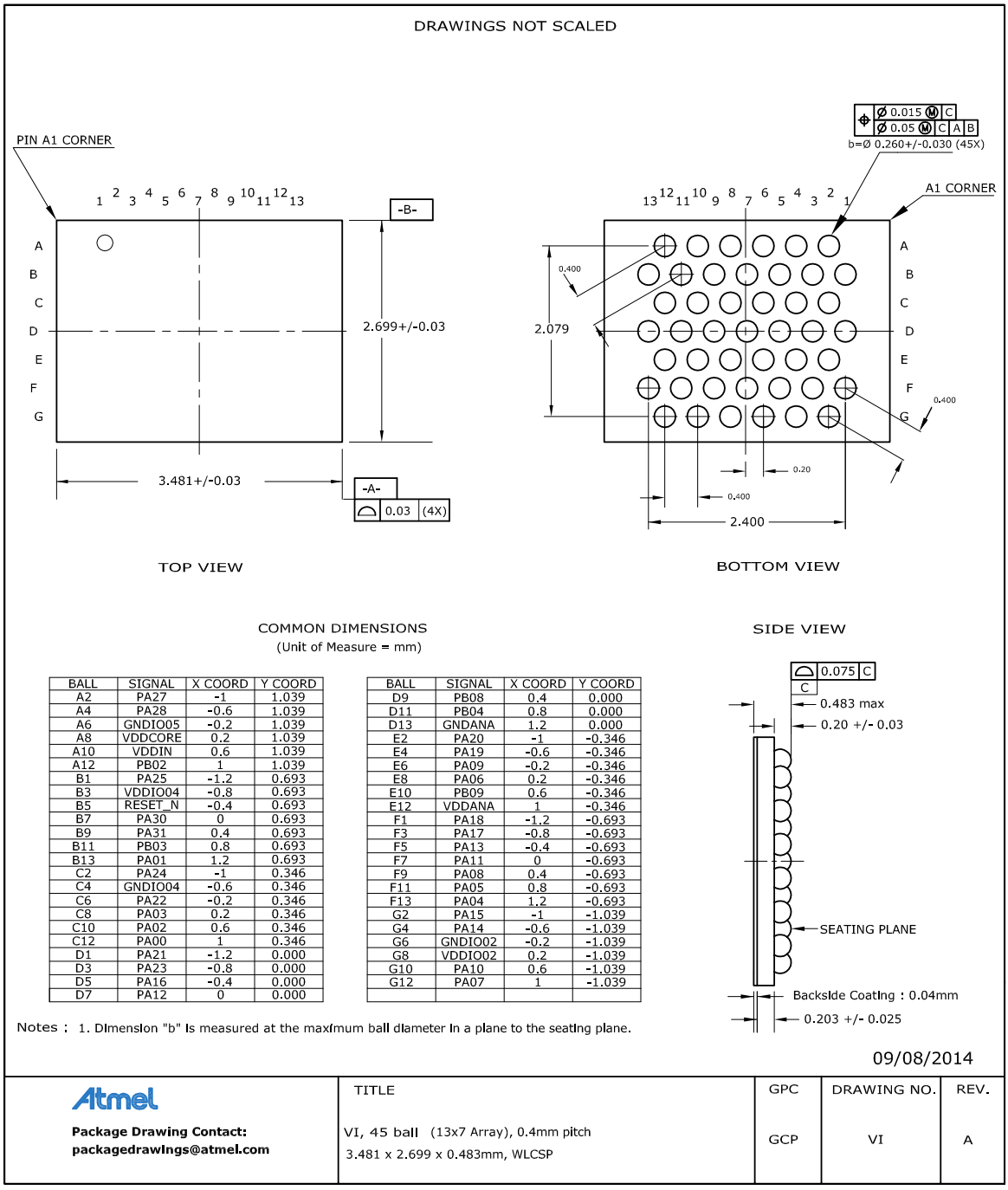
Table 7-15. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 7-16. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

7.2.6 45-ball WLCSP



BALL	SIGNAL	X COORD	Y COORD
A2	PA27	-1	1.039
A4	PA28	-0.6	1.039
A6	GNDIO05	-0.2	1.039
A8	VDDCORE	0.2	1.039
A10	VDDIN	0.6	1.039
A12	PB02	1	1.039
B1	PA25	-1.2	0.693
B3	VDDIO04	-0.8	0.693
B5	RESET_N	-0.4	0.693
B7	PA30	0	0.693
B9	PA31	0.4	0.693
B11	PB03	0.8	0.693
B13	PA01	1.2	0.693
C2	PA24	-1	0.346
C4	GNDIO04	-0.6	0.346
C6	PA22	-0.2	0.346
C8	PA03	0.2	0.346
C10	PA02	0.6	0.346
C12	PA00	1	0.346
D1	PA21	-1.2	0.000
D3	PA23	-0.8	0.000
D5	PA16	-0.4	0.000
D7	PA12	0	0.000

BALL	SIGNAL	X COORD	Y COORD
D9	PB08	0.4	0.000
D11	PB04	0.8	0.000
D13	GNDANA	1.2	0.000
E2	PA20	-1	-0.346
E4	PA19	-0.6	-0.346
E6	PA09	-0.2	-0.346
E8	PA06	0.2	-0.346
E10	PB09	0.6	-0.346
E12	VDDANA	1	-0.346
F1	PA18	-1.2	-0.693
F3	PA17	-0.8	-0.693
F5	PA13	-0.4	-0.693
F7	PA11	0	-0.693
F9	PA08	0.4	-0.693
F11	PA05	0.8	-0.693
F13	PA04	1.2	-0.693
G2	PA15	-1	-1.039
G4	PA14	-0.6	-1.039
G6	GNDIO02	-0.2	-1.039
G8	VDDIO02	0.2	-1.039
G10	PA10	0.6	-1.039
G12	PA07	1	-1.039

Table 7-17. Device and Package Maximum Weight

7.3	mg

Table 7-18. Package Characteristics

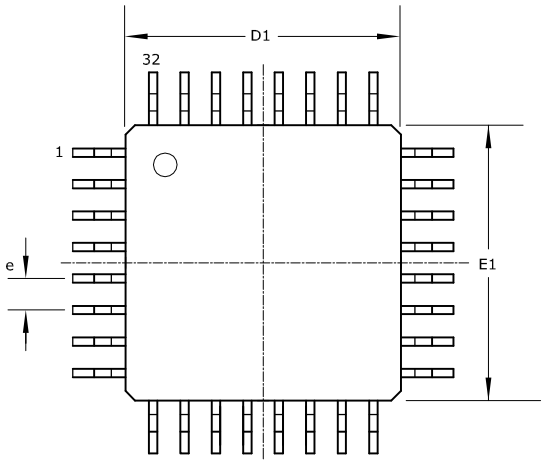
Moisture Sensitivity Level	MSL1

Table 7-19. Package Reference

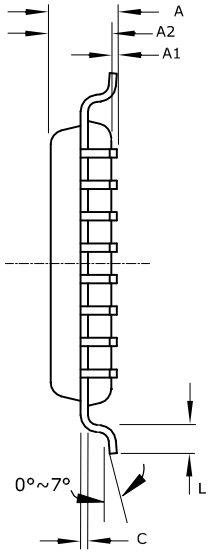
JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

7.2.7 32-pin TQFP

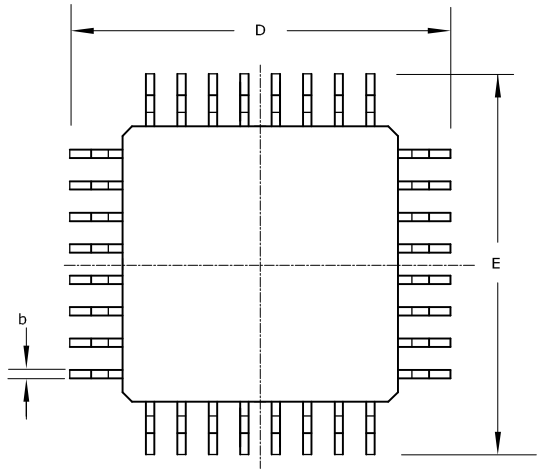
DRAWINGS NOT SCALED



TOP VIEW



SIDE VIEW



BOTTOM VIEW

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.05	-----	0.15	
A2	0.95	1.00	1.05	
D/E	8.75	9.00	9.25	
D1/E1	6.90	7.00	7.10	2
C	0.09	-----	0.20	
L	0.45	-----	0.75	
b	0.30	-----	0.45	
e	0.80 TYP			
n	32			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Varfation ABA.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

Table 7-20. Device and Package Maximum Weight

100	mg

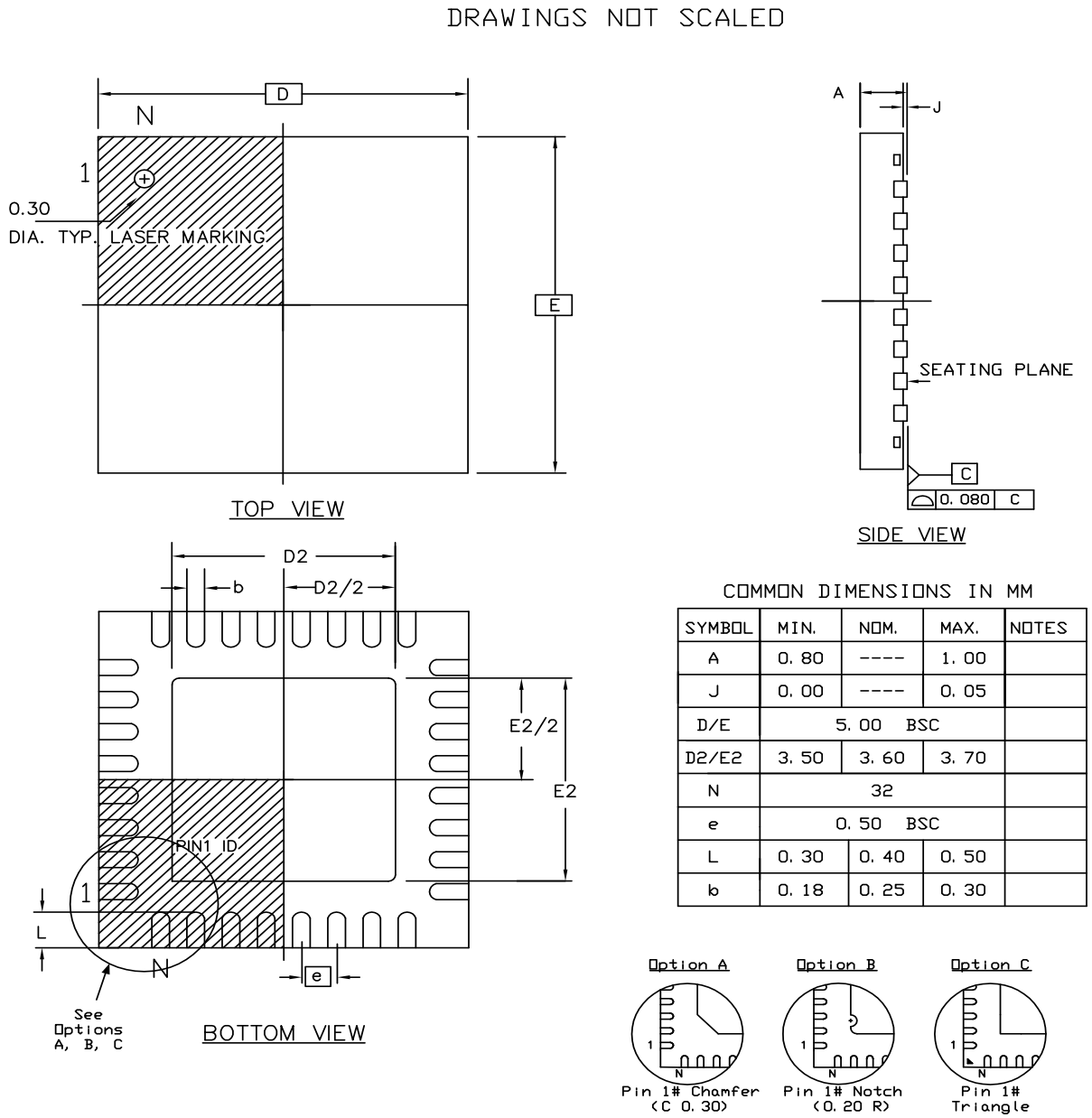
Table 7-21. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 7-22. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

7.2.8 32-pin QFN



SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	----	1.00	
J	0.00	----	0.05	
D/E		5.00 BSC		
D2/E2	3.50	3.60	3.70	
N		32		
e		0.50 BSC		
L	0.30	0.40	0.50	
b	0.18	0.25	0.30	

Table 7-23. Device and Package Maximum Weight

90	mg

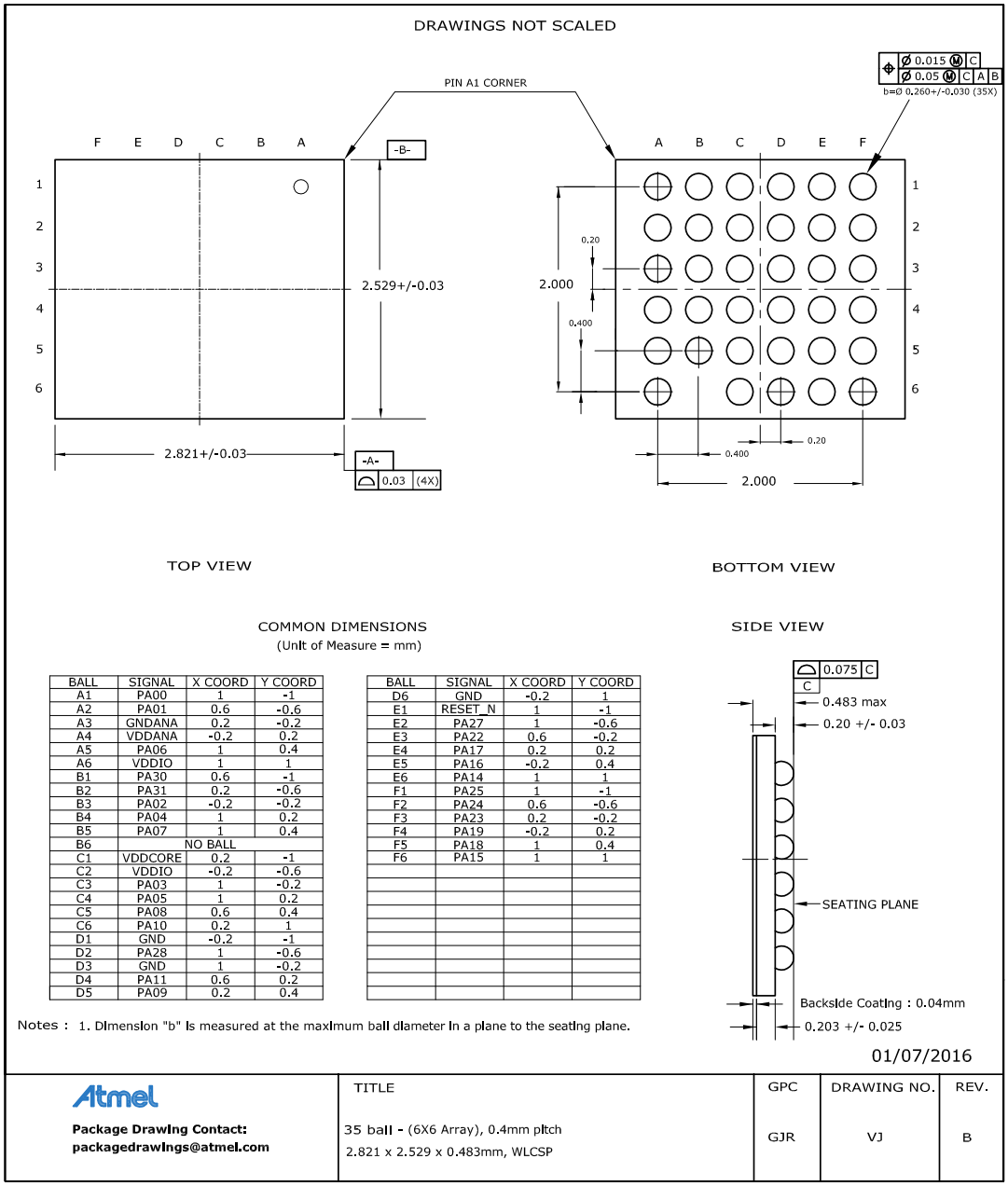
Table 7-24. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 7-25. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

7.2.9 35-ball WLCSP



BALL	SIGNAL	X COORD	Y COORD
A1	PA00	1	-1
A2	PA01	0.6	-0.6
A3	GNDANA	0.2	-0.2
A4	VDDANA	-0.2	0.2
A5	PA06	1	0.4
A6	VDDIO	1	1
B1	PA30	0.6	-1
B2	PA31	0.2	-0.6
B3	PA02	-0.2	-0.2
B4	PA04	1	0.2
B5	PA07	1	0.4
B6	NO BALL		
C1	VDDCORE	0.2	-1
C2	VDDIO	-0.2	-0.6
C3	PA03	1	-0.2
C4	PA05	1	0.2
C5	PA08	0.6	0.4
C6	PA10	0.2	1
D1	GND	-0.2	-1
D2	PA28	1	-0.6
D3	GND	1	-0.2
D4	PA11	0.6	0.2
D5	PA09	0.2	0.4

BALL	SIGNAL	X COORD	Y COORD
D6	GND	-0.2	1
E1	RESET_N	1	-1
E2	PA27	1	-0.6
E3	PA22	0.6	-0.2
E4	PA17	0.2	0.2
E5	PA16	-0.2	0.4
E6	PA14	1	1
F1	PA25	1	-1
F2	PA24	0.6	-0.6
F3	PA23	0.2	-0.2
F4	PA19	-0.2	0.2
F5	PA18	1	0.4
F6	PA15	1	1

Table 7-26. Device and Package Maximum Weight

6.2	mg

Table 7-27. Package Characteristics

Moisture Sensitivity Level	MSL1

Table 7-28. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

7.3 Soldering Profile

The following table gives the recommended soldering profile from J-STD-20.

Profile Feature	Green Package
Average Ramp-up Rate (217°C to peak)	3°C/s max
Preheat Temperature 175°C +/-25°C	150-200°C
Time Maintained Above 217°C	60-150s
Time within 5°C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s max
Time 25°C to Peak Temperature	8 minutes max

A maximum of three reflow passes is allowed per component.

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